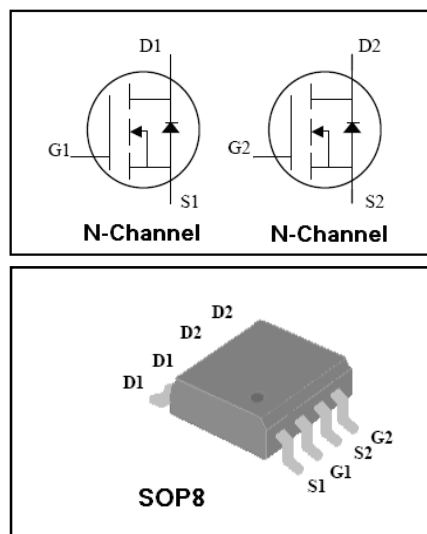


**Features**

- ◆ BVDSS > 30V, R<sub>DS(ON)</sub>=21mΩ(Typ)@V<sub>GS</sub>=10V
- ◆ Low On-Resistance
- ◆ Fast Switching
- ◆ Lead-Free,Hg-Free, Green Product

PTS4842 designed by the trench processing techniques to achieve extremely low on-resistance. And fast switching speed and improved transfer effective . These features combine to make this design an extremely efficient and reliable device for variety of DC-DC applications.

**Pin Description**



**Absolute Maximum Ratings (T<sub>c</sub>=25°C Unless Otherwise Noted)**

Symbol	Parameter		Rating	Unit
V <sub>GS</sub>	Gate-Source Voltage		±20	V
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage		30	V
T <sub>J</sub>	Maximum Junction Temperature		150	°C
T <sub>STG</sub>	Storage Temperature Range		-50 to 150	°C
I <sub>S</sub>	Diode Continuous Forward Current	T <sub>c</sub> =25°C	5	A
<b>Mounted on Large Heat Sink</b>				
I <sub>DM</sub>	Pulse Drain Current Tested <sup>(Note 1)</sup>	T <sub>c</sub> =25°C	30	A
I <sub>D</sub>	Continuous Drain Current(V <sub>GS</sub> =10V)	T <sub>c</sub> =25°C	7.7	A
		T <sub>c</sub> =100°C	6.5	
P <sub>D</sub>	Maximum Power Dissipation	T <sub>c</sub> =25°C	2	W
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient		89	°C/W

## 30V/7.7A Dual N-Channel Advanced Power MOSFET

Static Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	30	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V	--	--	1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	1.6	2.5	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =7.7A	--	16	21	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =5V, I <sub>D</sub> =5A	--	20	30	mΩ

Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz	--	420	--	pF
C <sub>oss</sub>	Output Capacitance		--	85	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	9	--	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =15V, I <sub>D</sub> =4A, V <sub>GS</sub> =4.5V	--	10.5	--	nC
Q <sub>gs</sub>	GateSource Charge		--	2.3	--	nC
Q <sub>gd</sub>	GateDrain Charge		--	3	--	nC

## Switching Characteristics

t <sub>d(on)</sub>	Turnon Delay Time	V <sub>DD</sub> =15V, I <sub>D</sub> =3A, R <sub>G</sub> =3.3Ω, V <sub>GS</sub> =10V	--	4.5	--	ns
t <sub>r</sub>	Turnon Rise Time		--	3	--	ns
t <sub>d(off)</sub>	TurnOff Delay Time		-	12	--	ns
t <sub>f</sub>	TurnOff Fall Time		--	2	--	ns

## Source Drain Diode Characteristics

I <sub>SD</sub>	Sourcedrain current(Body Diode) <sup>①</sup>	T <sub>c</sub> =25°C	--	--	5	A
V <sub>SD</sub>	Forward on voltage	T <sub>j</sub> =25°C, I <sub>SD</sub> =4A, V <sub>GS</sub> =0V	--	0.82	1.2	V

## Notes:

- ① Pulse test ; Pulse width≤300μs, duty cycle≤2%.
- ② Pulse width limited by maximum allowable junction temperature

Typical Characteristics

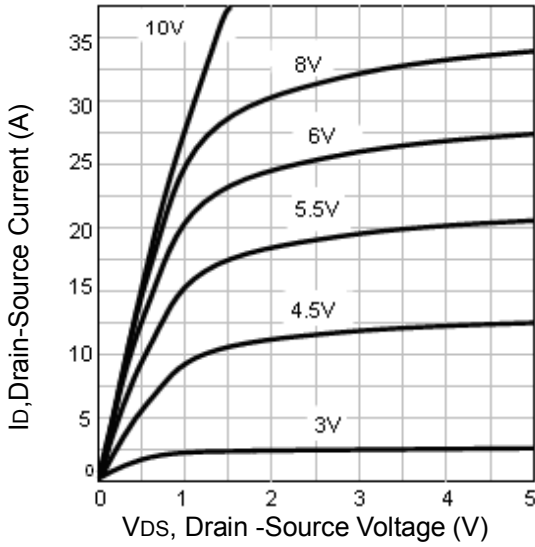


Fig1. Typical Output Characteristics

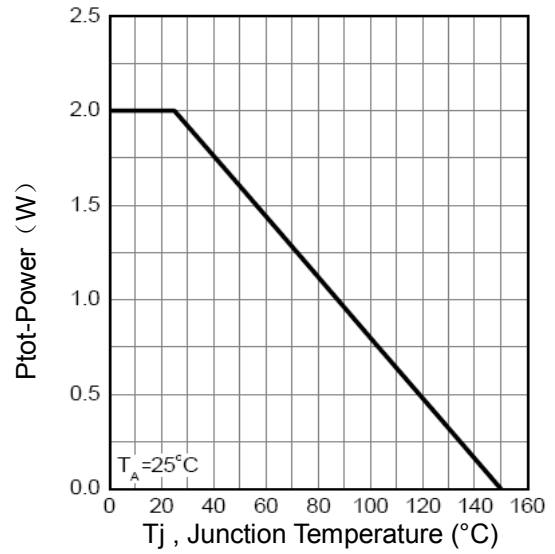


Fig2. Power Dissipation

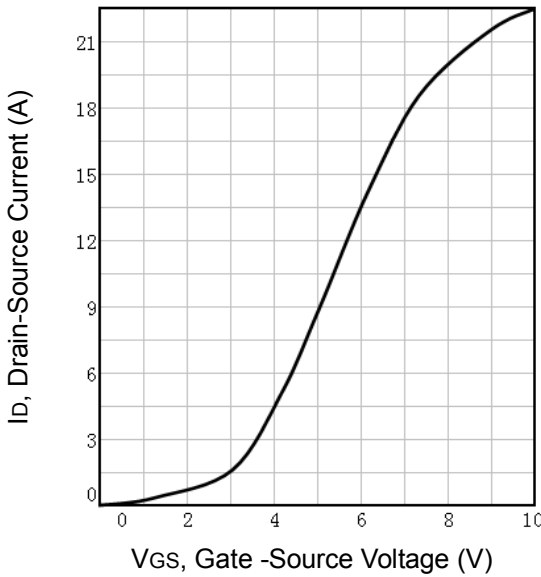


Fig3. Typical Transfer Characteristics

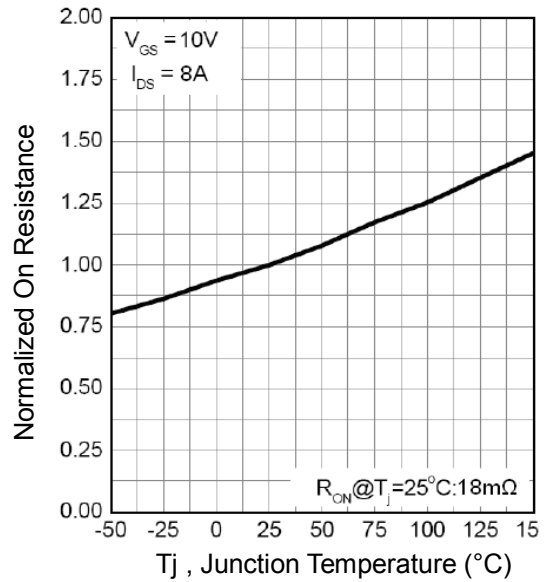


Fig4. Normalized On-Resistance Vs. Temperature

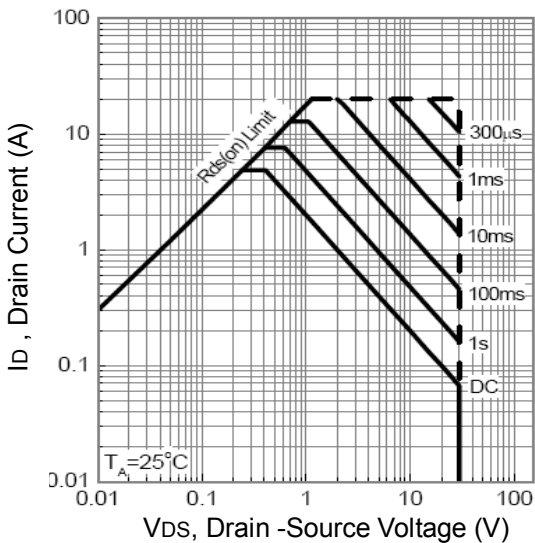


Fig5. Maximum Safe Operating Area

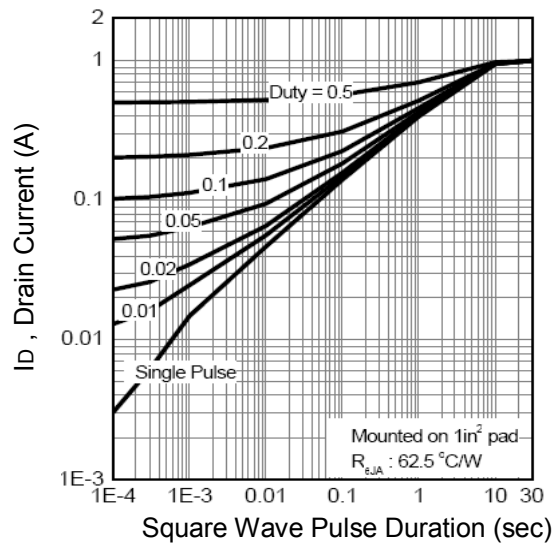


Fig6. Thermal Transient Impedance

Typical Characteristics

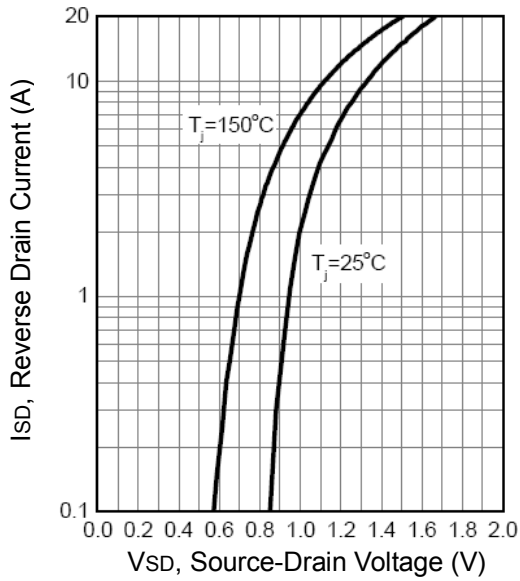


Fig7. Typical Source-Drain Diode Forward Voltage

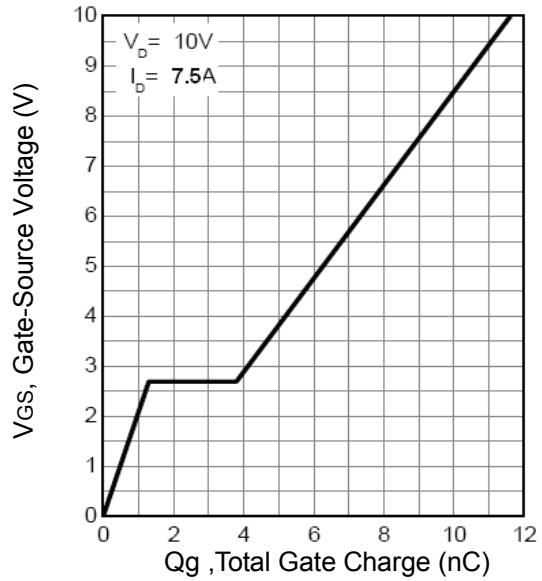


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

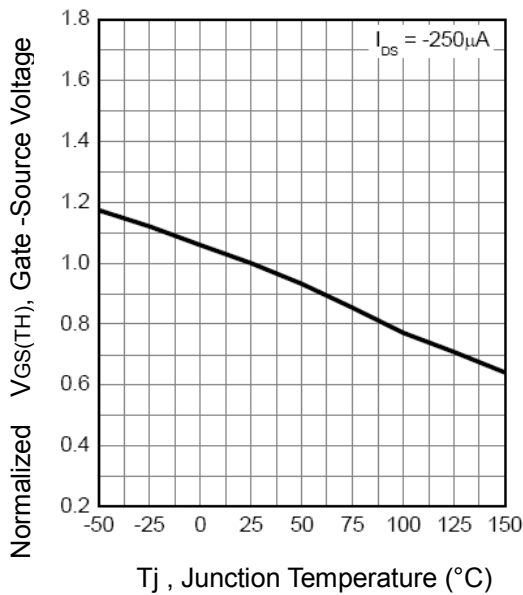


Fig9. Threshold Voltage Vs. Temperature

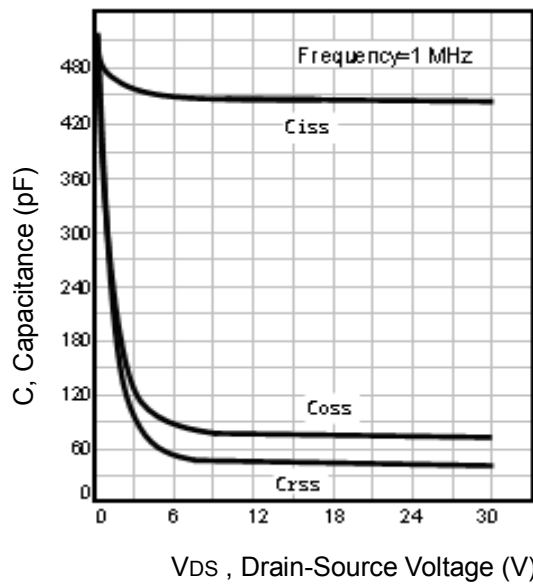


Fig10. Typical Capacitance Vs. Drain-Source Voltage

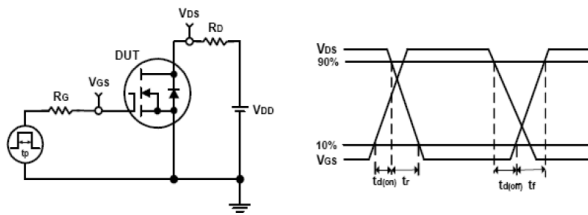


Fig11. Switching Time Test Circuit and waveforms